L	Hits	Search Text	DB	Time stamp
Number				
1	3	5198964.pn.	USPAT;	2002/06/24
1		013030117111	US-PGPUB;	22:05
		·	EPO; JPO;	
			DERWENT;	
			IBM TDB	
•	4650728	gold au	USPAT;	2002/06/24
2	4650720	goid ad	US-PGPUB;	22:05
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_		5100064 and (gold by)	USPAT;	2002/06/24
3	1	5198964.pn. and (gold au)	US-PGPUB;	22:11
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
			USPAT;	2002/06/24
4	1134943	lead leadframe (lead adj frame)	US-PGPUB;	22:12
			EPO; JPO;	22.12
			DERWENT;	ļ
ľ				
		17	IBM_TDB USPAT;	2002/06/24
5	5876	(lead leadframe (lead adj frame)) with	USPAI; US-PGPUB;	22:13
		(plated plating covered layer) with (gold	EPO; JPO;	22.13
		au)	1	
			DERWENT;	
			IBM_TDB USPAT;	2002/06/24
6	997	((lead leadframe (lead adj frame)) with	US-PGPUB;	22:13
		(plated plating covered layer) with (gold		22.13
		au)) same solder	EPO; JPO;	
			DERWENT;	
			IBM_TDB	2002/06/24
7	2119145	semiconductor die chip ic dice	USPAT;	2002/06/24
		(integrated adj circuit)	US-PGPUB;	22.13
			EPO; JPO;	
			DERWENT;	
1			IBM_TDB	2002/06/24
8	496	package and (((lead leadframe (lead adj	USPAT;	2002/06/24
		frame)) with (plated plating covered	US-PGPUB;	22:15
1		layer) with (gold au)) same solder)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	0000 (06 (04
9	462	(semiconductor die chip ic dice	USPAT;	2002/06/24
		(integrated adj circuit)) and (package	US-PGPUB;	22:16
		and (((lead leadframe (lead adj frame))	EPO; JPO;	
		with (plated plating covered layer) with	DERWENT;	
1		(gold au)) same solder))	IBM_TDB	